

## **Materials Declaration Form**

IPC	1752	Version	2
Form Type *	Distribute	Telsion.	-
Sectionals *	Material Info	Subsectionals *	A-D
	Manufacturing Info		* : Required Field

Supplier Information							
Company Name *	STMicroelectronics Response Date *		25-08-2017				
Company Unique ID	NL 008751171B01						
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section				
Contact Phone *	Refer to Supplier Comment section Contact Email *		Refer to Supplier Comment section				
Authorized Representative *	MDG MD CHAMPION Representative Title		MDG MD CHAMPION				
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section				
Supplier Comment	* * * * * * * * * * * * * * * * * * * *	line Technical Support - STMicroelectronics : :p://www.st.com/web/en/support/support.html					

## **Uncertainty Statement**

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Legal Stateme	ent			

Supplier Acceptance \* true Legal Declaration \* Standard

## Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product								
Mfr Item Number Mfr Item Name		Version	Mfr Site	Date				
STR731FV0T6	AA1L*403XXXY	А	1054	25-08-2017				
	Amount	UoM	Unit type	ST ECOPACK Grade				
	650.00	mg Each		ECOPACK® 2				
		ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retar ( in each organic material)						

Manufacturing information							
J-STD-020 MSL Rating Classification Temp		Nbr of Reflow Cycles					
3	260	3					
bulk Solder Termination Terminal Plating		Terminal Base Alloy	Comment	life.augmented			
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		and the state of t			

Package Designator	Size	Nbr of instances	Shape	
QFP	14x14x1.4	100	L Bend	
Comment	Package: 1L LQFP 100 14x14x1.4 1 00	86901		

QueryList: RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015							
	Query	Response					
1 - Product(s) meets EU RoHS requirement without any exemptions							
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may							
apply)		FALSE					
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s) FALSE							
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions FALSE							
Exemption Id. Description							

QueryList: REACH-12th January 2017							
Query Response							
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH							
CategoryLevel_Name CategoryLevel_Threshold amount in product (mg) Application							

Material Composition Declaration: note: Substance present with less 0.001mg will not be declared in this document			Mfr Item Name	AA1L*403XXXY				6999998.0	1000003.0			
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	25.872	mg	supplier	die	Silicon (Si)	7440-21-3		25.169	mg	972828	38722
				supplier	metallization	Aluminium (AI)	7429-90-5		0.101	mg	3904	155
				supplier	metallization	Cobalt (Co)	7440-48-4		0.002	mg	77	3
				supplier	metallization	Titanium (Ti)	7440-32-6		0.027	mg	1044	42
				supplier	metallization	Tungsten (W)	7440-33-7		0.020	mg	773	31
				supplier	Passivation	Silicon Nitride	12033-89-5		0.057	mg	2203	88
				supplier	Passivation	Silicon Oxide	7631-86-9		0.496	mg	19171	763
Lead-frame	M-011 Other inorganic materials	134.439	mg	supplier	alloy	Copper (Cu)	7440-50-8		131.011	mg	974500	201556
					alloy	Iron (Fe)	7439-89-6		3.081	mg	22920	4741
					alloy	Zinc (Zn)	7440-66-6		0.161	mg	1200	248
					alloy	Iron Phosphide (Fe2P)	1310-43-6		0.186	mg	1380	285
Lead-frame Coating	M-011 Other inorganic materials	0.559	mg	supplier	coating	Nickel (Ni)	7440-02-0		0.520	mg	930510	800
					coating	Palladium (Pd)	7440-05-3		0.021	mg	37710	32
					coating	Gold (Au)	7440-57-5		0.018	mg	31780	27
Die Attach	M-011 Other inorganic materials	2.324	mg	supplier	glue or soft solder	Silver (Ag)	7440-22-4		1.834	mg	789474	2822
					glue or soft solder	Acrylate	Proprietary		0.163	mg	70175	251
					glue or soft solder	Methacrylate	Proprietary		0.163	mg	70175	251
					glue or soft solder	Acrylate	Proprietary		0.163	mg	70175	251
Wires	M-011 Other inorganic materials	1.670	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		1.653	mg	990000	2543
					Bonding wire	Palladium (Pd)	7440-05-3		0.017	mg	10000	26
Encapsulation	M-011 Other inorganic materials	485.132	mg	supplier	Moulding Compound	Solid Epoxy Resin	Proprietary		35.068	mg	72285	53951
					Moulding Compound	Phenol Resin	Proprietary		25.048	mg	51632	38536
					Moulding Compound	Silica, vitreous	60676-86-0		417.501	mg	860593	642310
					Moulding Compound	Carbon-black	1333-86-4		2.505	mg	5163	3854
					Bismuth/Bismuth Compounds	Bismuth	7440-69-9		5.010	mg	10326	7707
Finishing	M-011 Other inorganic materials	0.006	mg	supplier	connections coating	Nickel (Ni)	7440-02-0		0.005	mg	930510	8
					connections coating	Palladium (Pd)	7440-05-3		0.000	mg	37710	0
					connections coating	Gold (Au)	7440-57-5		0.000	mg	31780	0